



SOD57

hermetically sealed glass package; axial leaded; 2 leads

16 October 2018

Package information

1 Package summary

Terminal position code	A (axial)
Package type descriptive code	GALF2
Package type industry code	GALF2
Package style descriptive code	LALF (glass axial (leaded) long form)
Package body material type	L (glass)
Mounting method type	T (through-hole mount)
Issue date	14-10-1997
Manufacturer package code	SOD57

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	4.57	-	mm
package diameter	-	3.81	-	mm
actual quantity of termination	-	2	-	



2 Package outline

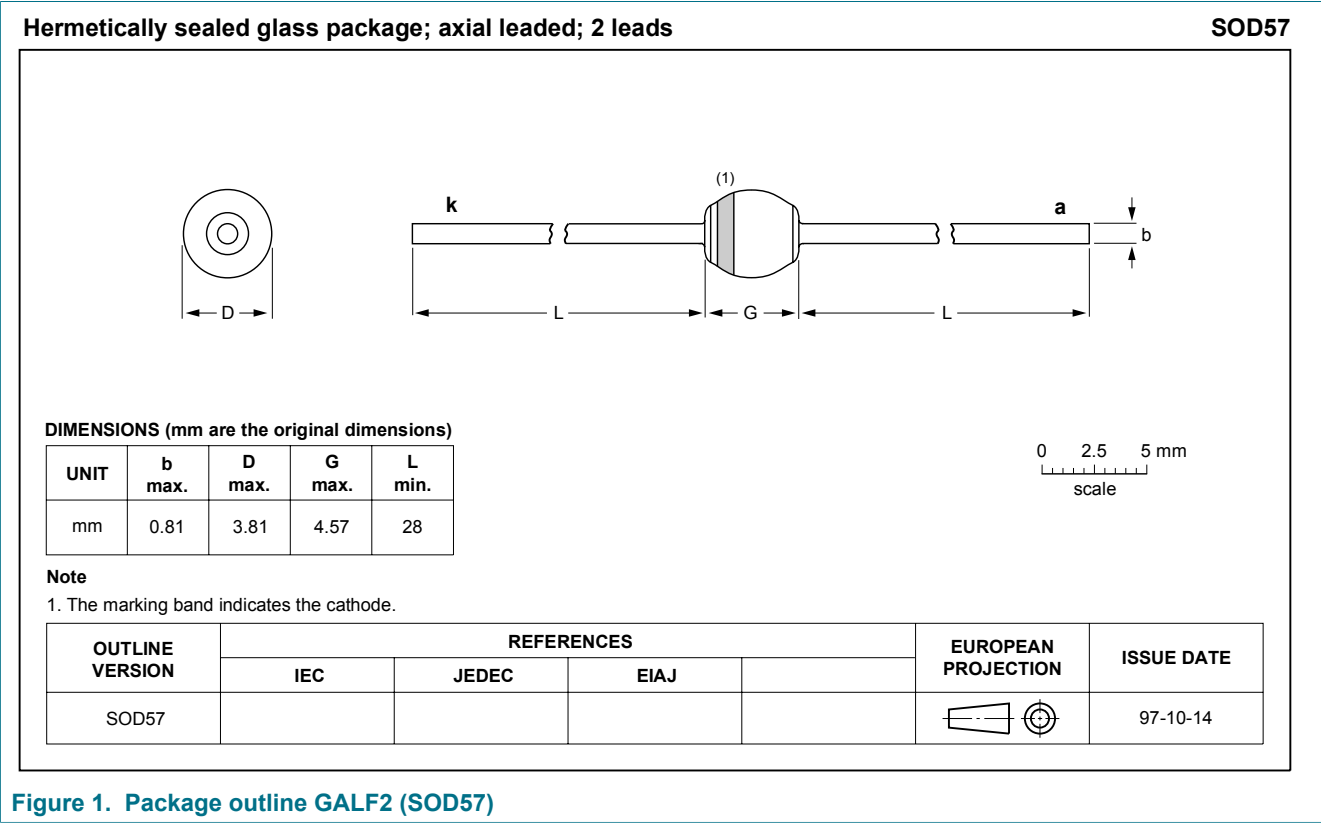


Figure 1. Package outline GALF2 (SOD57)

3 Legal information

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